PRESS RELEASE
August 2024

IMAPS 57th International Symposium on Microelectronics Planned for September 30 - October 3, 2024, in Boston, Massachusetts

The 57th International Symposium on Microelectronics (IMAPS 2024) will be held September 30 - October 3, 2024, at the Encore Boston Harbor in Boston, Massachusetts. This highly regarded annual conference brings together industry engineers, top experts, researchers and students involved in advanced packaging and microelectronics assembly.

IMAPS 2024 will offer one of the most robust technical programs in the industry, which includes a concurrent 5-track program with over 120 speakers and poster presentations covering topics related SiP/Design/Manufacturing Optimization; Wafer Level/Panel Level (Advanced RDL); High Performance/High Reliability; Advanced Package (Flip Chip, 2.5D, 3D, Optical); Advanced Process & Materials (Enabling Technologies).

Attendees can register for supplemental two-hour Professional Development Courses that provide a learning opportunity to enhance skills and grow career capabilities. This year's PDC topics include: Chiplet Design & Heterogeneous Integration; Fan-Out Wafer Level Packaging; Flip Chip, System-in-Package; Co-Packaged Optics, Thermal Management, Wire Bond, Materials and more.

New to this year's program: Special Onshoring sessions on Monday: (1) Buildup Substrates and (2) Glass Core, Si Interposers and Bridges; a Monday evening reception of fun networking, Bingo style, where all participants can expand their network and win prizes; and a Tuesday afternoon 3D InCites Community Career Fair open to students and industry attendees.

The agenda includes six keynotes presented by industry experts from CHIPS NAPMP, Heraeus Electronics, Lightmatter, Qorvo, Samsung Electronics and Zero ASIC, and a panel session on RDL Packaging for High Performance Applications.

The sold-out exhibit hall will feature 90 exhibitors showcasing product and service offerings of the current technologies and applications.

This year's General Chair, Tarak Railkar with Qorvo, said, "I am incredibly delighted to invite colleagues from the industry, research institutions as well as academia to IMAPS-2024, which is being organized at a brand-new location in Boston! With machine learning and artificial intelligence poised to bring transformational changes to just about everything we know, the symposium will address key enablers such as heterogeneous integration, photonics – and onshoring. The entire team and I look forwarding to welcoming first-time and many repeat attendees in Boston!"

In 2023, nearly 800 people participated in the Symposium in San Diego, including 87 from outside the US. There was great student participation with university booths, student speakers and visiting high school students. It is anticipated that 2024 will surpass last year's numbers.

Conference details and registration are available at www.IMAPS2024.org

About IMAPS

The International Microelectronics Assembly and Packaging Society is the largest society dedicated to the advancement and growth of microelectronics and electronics packaging. Worldwide, IMAPS offers educational and marketing opportunities for industry professionals, packaging organizations, and students through technical conferences and workshops, professional development courses, IMAPSource microelectronics packaging research library, local chapters and exhibitions. The Society encompasses a wide-range of technologies and topics critical to microelectronics assembly and packaging, including: on-shoring, heterogenous integration, fan-out wafer level packaging, 2.5D/3D technologies, system-in-package, photonics/optical, power packaging, CPI, package design/modeling, interconnects, wire bonding, flip chip, MEMS, sensors, packaging for 5g/6g, RF/wireless, signal/power integrity, advanced materials, substrates and more.

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